



# NPN/PNP Silicon Complementary Small Signal Dual Transistor *Qualified per MIL-PRF-19500/421*

## DESCRIPTION

This 2N4854 device in a 6-pin TO-78 package is military qualified up to a JANTXV level for high-reliability applications. Microsemi also offers numerous other products to meet higher and lower power voltage regulation applications.

Important: For the latest information, visit our website http://www.microsemi.com.

FEATURES

- JEDEC registered 2N4854.
- JAN, JANTX, and JANTXV qualifications also available per MIL-PRF-19500/421.
- RoHS compliant versions available (commercial grade only).

#### **APPLICATIONS / BENEFITS**

- Compact package design.
- Lightweight.

## MAXIMUM RATINGS

Parameters/Test Conditions	Symbol	Value per		Unit
		Each Transistor	Total Package	
Thermal Resistance Junction-to-Case	R <sub>eJC</sub>	175	87	°C/W
Thermal Resistance Junction-to-Ambient	R <sub>θJA</sub>	350	290	°C/W
Total Power Dissipation @ $T_A = +25  {}^{\circ}C^{(1)}$	Pτ	0.30	0.60	W
Total Power Dissipation @ $T_c$ = +25 °C <sup>(2)</sup>	Pτ	1.0	2.0	W
Junction and Storage Temperature	T <sub>J</sub> and T <sub>STG</sub>	-65 to +200		°C
Collector-Base Voltage, Emitter Open	V <sub>сво</sub>	60		V
Emitter-Base Voltage, Collector Open	V <sub>EBO</sub>	5		V
Collector-Emitter Voltage, Base Open	V <sub>CEO</sub>	40		V
Collector Current, dc	Ι <sub>C</sub>	600		mA
Lead to Case Voltage		+/- 120		V
Solder Temperature @ 10 s	T <sub>SP</sub>	260		°C

**Notes:** 1. For  $T_A > +25^{\circ}$ C, derate linearly 1.71 mW/°C one transistor, 3.43 mW/°C both transistors. 2. For  $T_C > +25^{\circ}$ C, derate linearly 5.71 mW/°C one transistor, 11.43 mW/°C both transistors. <u>Qualified Levels:</u> JAN, JANTX, and JANTXV



# TO-78 Package

## Also available in:

b-Pin U package <u>2N4854U</u>

6-Pin Flatpack package <u>2N3838</u>

#### MSC – Lawrence

6 Lake Street, Lawrence, MA 01841 Tel: 1-800-446-1158 or (978) 620-2600 Fax: (978) 689-0803

#### MSC – Ireland

Gort Road Business Park, Ennis, Co. Clare, Ireland Tel: +353 (0) 65 6840044 Fax: +353 (0) 65 6822298

Website:

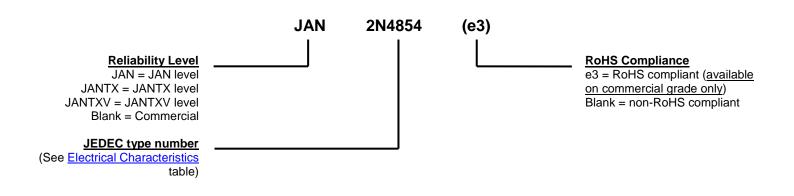
www.microsemi.com



#### **MECHANICAL and PACKAGING**

- CASE: Au over Ni plated kovar, pure nickel cap.
- TERMINALS: Au over Ni plated kovar.
- MARKING: Manufacturer's ID, part number, date code.
- POLARITY: See case outline.
- WEIGHT: 0.856 grams.
- See <u>Package Dimensions</u> on last page.

### PART NOMENCLATURE



	SYMBOLS & DEFINITIONS				
Symbol	Definition				
Ι <sub>Β</sub>	Base Current, dc.				
lc	Collector Current, dc.				
Ι <sub>Ε</sub>	Emitter Current, dc.				
Io	Average Rectified Output Current: The Output Current averaged over a full cycle with a 50 Hz or 60 Hz sine-wave input and a 180 degree conduction angle.				
V <sub>CB</sub>	Collector-Base Voltage (dc).				
V <sub>CE</sub>	Collector-Emitter Voltage, dc.				
V <sub>EB</sub>	Emitter-Base Voltage (dc).				

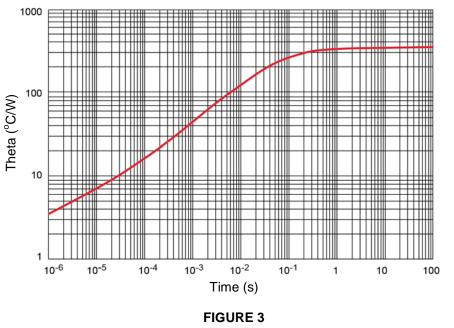


Characteristics	Symbol	Min.	Max.	Unit
OFF CHARACTERISTICS				
Collector-Emitter Breakdown Current	M	40		V
$I_{\rm C} = 10 \text{ mA} \text{ (pulsed)}$	V <sub>(BR)CEO</sub>	40		V
Collector-Base Cutoff Current	les eur		10	^
$V_{CB} = 60 V$	I <sub>CBO(1)</sub>		10	μA
Collector-Base Cutoff Current	lasa (s)		10	n۸
$V_{CB} = 50 V$	I <sub>CBO(2)</sub>		10	nA
Emitter-Base Cutoff Current				
$V_{EB} = 5.0 V$	I <sub>EBO(1)</sub>		10	μA
V <sub>EB</sub> = 3.0 V	I <sub>EBO(2)</sub>		10	nA
ON CHARACTERISTICS				
Forward-Current Transfer Ratio				
$I_{C} = 150 \text{ mA}, V_{CE} = 1 \text{ V}$	h <sub>FE</sub>	50		
$I_{C} = 100 \ \mu A, \ V_{CE} = 10 \ V$		35		
$I_{\rm C}$ = 1.0 mA, $V_{\rm CE}$ = 10 V		50		
$I_{C} = 10 \text{ mA}, V_{CE} = 10 \text{ V}$		75		
I <sub>C</sub> = 150 mA, V <sub>CE</sub> = 10 V		100	300	
I <sub>C</sub> = 300 mA, V <sub>CE</sub> = 10 V		35		
Collector-Emitter Saturation Voltage	V <sub>CE(sat)</sub>		0.40	V
I <sub>C</sub> = 150 mA, I <sub>B</sub> = 15 mA	VCE(sat)		0.40	v
Base-Emitter Saturation Voltage	V <sub>BE(sat)</sub>	0.80	1.25	V
I <sub>C</sub> = 150 mA, I <sub>B</sub> = 15 mA	VBE(sat)	0.00	1.20	v
DYNAMIC CHARACTERISTICS				
Forward Current Transfer Ratio	h <sub>fe</sub>	60	300	
I <sub>C</sub> = 1.0 mA, V <sub>CE</sub> = 10 V, f = 1.0 kHz	ine	00	000	
Forward Current Transfer Ratio, Magnitude	h <sub>fe</sub>	2.0	10	
I <sub>C</sub> = 20 mA, V <sub>CE</sub> = 10 V, f = 100 MHz	l'itel	2.0	10	
Small-Signal Common Emitter Input Impedance	h.,	4.5	0.0	kΩ
$I_{C} = 1.0 \text{ mA}, V_{CE} = 10 \text{ V}, f = 1.0 \text{ kHz}$	h <sub>ie</sub>	1.5	9.0	K12
Small-Signal Common Emitter Output Admittance				
$I_{\rm C} = 1.0$ mA, $V_{\rm CE} = 10$ V, f = 1.0 kHz	hoe		50	μhmo
Open Circuit Output Capacitance				
$V_{CB} = 10 \text{ V}, I_E = 0, 100 \text{ kHz} \le f \le 1.0 \text{ MHz}$	Cobo		8.0	pF
	NF		8.0	dB
$I_{C} = 100 \ \mu\text{A}, \ V_{CE} = 10 \ V, \ f = 1.0 \ \text{kHz}, \ R_{G} = 1.0 \ \text{k}\Omega$				
SWITCHING CHARACTERISTICS		1		-
Turn-On Time (Saturated)	ton		45	ns
(Reference MIL-PRF-19500/421, figure 7)	011			
Turn-Off Time (Saturated)	toff		300	ns
(Reference MIL-PRF-19500/421, figure 8)				
Pulse Response (Non-Saturated)	ton + toff		18	ns
(Reference MIL-PRF-19500/421, figure 9)				
Collector-Emitter Non-Latching Voltage	V <sub>CEO</sub>	40		V

# **ELECTRICAL CHARACTERISTICS** @ $T_A$ = 25 °C unless otherwise noted.



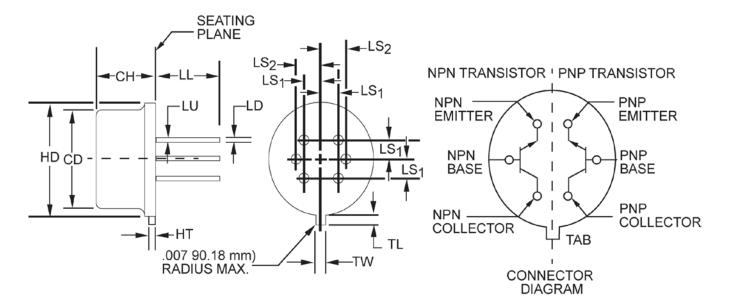
# GRAPHS



Thermal impedance graph (RøJA)



#### PACKAGE DIMENSIONS



	Dimensions				
Ltr	Inch		Millimeters		Notes
	Min	Max	Min	Max	
CD	.305	.335	7.75	8.51	
СН	.140	.260	3.56	6.60	
HD	.335	.370	8.51	9.40	
HT	.009	.125	0.23	3.18	
LD	.016	.021	0.41	0.53	3,7
LL	.500	1.750	12.70	44.45	7

	Dimensions				Notes
Ltr	Inch		Millimeters		
	Min	Max	Min	Max	
LS1	.0707 Nom.		1.796 Nom.		5
LS2	.1000 Nom.		2.540 Nom		5
LU	.016	.019	0.41	0.48	4, 7
TL	.029	.045	0.74	1.14	6
TW	.028	.034	0.71	0.86	

#### NOTES:

- 1. Dimensions are in inches.
- 2. Millimeters are given for general information only.
- 3. Measured in the zone beyond .250 inch (6.35 mm) from the seating plane.
- 4. Measured in the zone .050 inch (1.27 mm) and .250 inch (6.35 mm) from the seating plane.
- 5. When measured in a gauging plane .054 +.001, -.000 inch (1.37 +0.03, -0.00 mm) below the seating plane of the transistor, maximum diameter leads shall be within .007 inch (0.18 mm) of their true location relative to a maximum width tab. Smaller diameter leads shall fall within the outline of the maximum diameter lead tolerance.
- 6. Measured from the maximum diameter of the actual device.
- 7. All six leads.
- 8. In accordance with ASME Y14.5M, diameters are equivalent to  $\Phi x$  symbology.

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